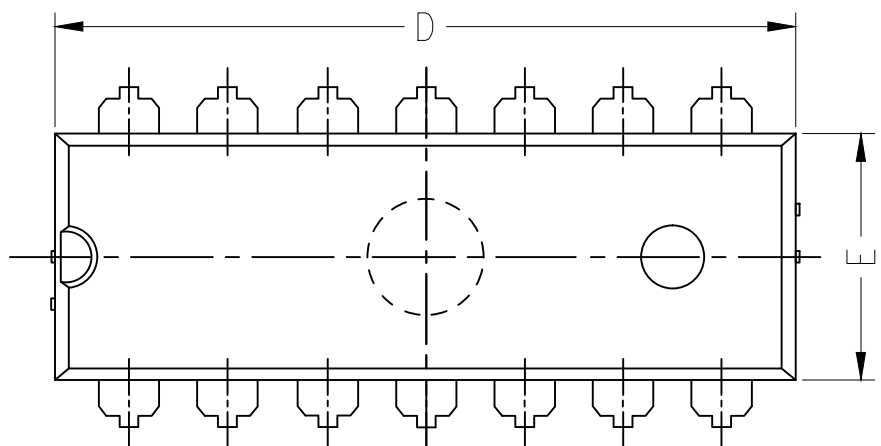
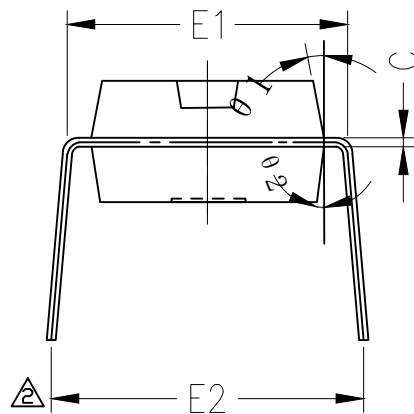
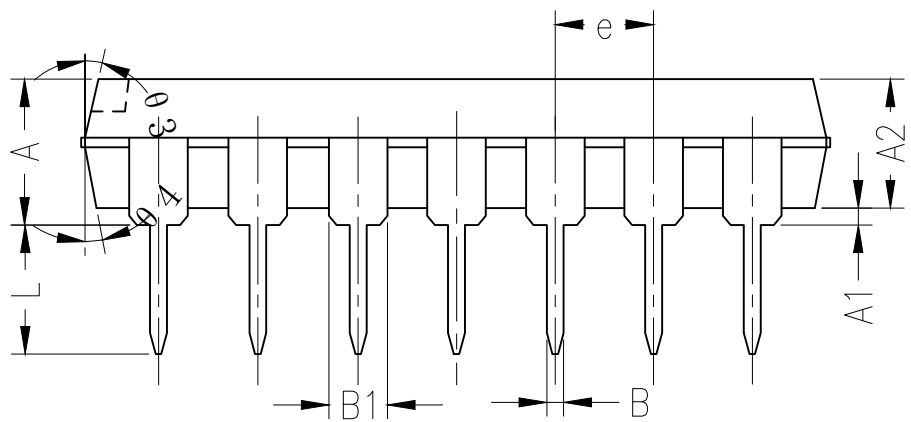




MARK	REVISION RECORD	VERSION	REVISERE
①	补加塑封体正面右边位置顶杆孔小圆;		
②	跨度由内缘标注改为外缘标注(管脚中间)	C	



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	3.75	3.81	3.95
A1	0.51	--	--
A2	3.20	3.30	3.45
B	0.38	0.48	0.56
B1	1.52(BSC)		
C	0.20	0.25	0.34
D	18.80	19.05	19.30
E	6.20	6.35	6.50
E1	7.35	7.62	7.85
e	2.54(BSC)		
L	3.00	3.20	3.60
E2	8.00	8.40	8.80
θ1	9°	~	15°
θ2	7°	~	13°
θ3	8°	~	14°
θ4	5°	~	12°

技术说明:

- LEADFRAME MATERIAL: COPPER;
引线框架材料: 铜;
- LEADFRAME THICKNESS: 0.254mm;
引线框架厚度: 0.254mm;
- BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;
塑封体长度及宽度尺寸不包括塑封溢胶;
- REFERENCE: JEDEC MS-013, MS-012.
参考标准: JEDEC MS-013, MS-012.

THIRD ANGLE PROJECTION		SCALE	UNIT	mm	TITLE
		DATE	2022-12-06		DIP14L产品成型图
TOLERANCE		DESIGNER	CHECKER	APPROVER	
		陈露			DWG.NO. MT-PD-030
		2022-12-06			VERSION C 第1页 共1页